



SOT1092-5

HVQFN36, plastic thermal enhanced very thin quad flat package; no leads, wettable flanks, 36 terminals; body 6 mm x 6 mm x 0.85 mm

11 September 2017

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN36
Package type industry code	HVQFN36
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	9-9-2017
Manufacturer package code	SOT1092-5

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	6	-	mm
E	package width	-	-	6	-	mm
A	seated height	-	-	0.85	-	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	36	-	



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2. Package outline

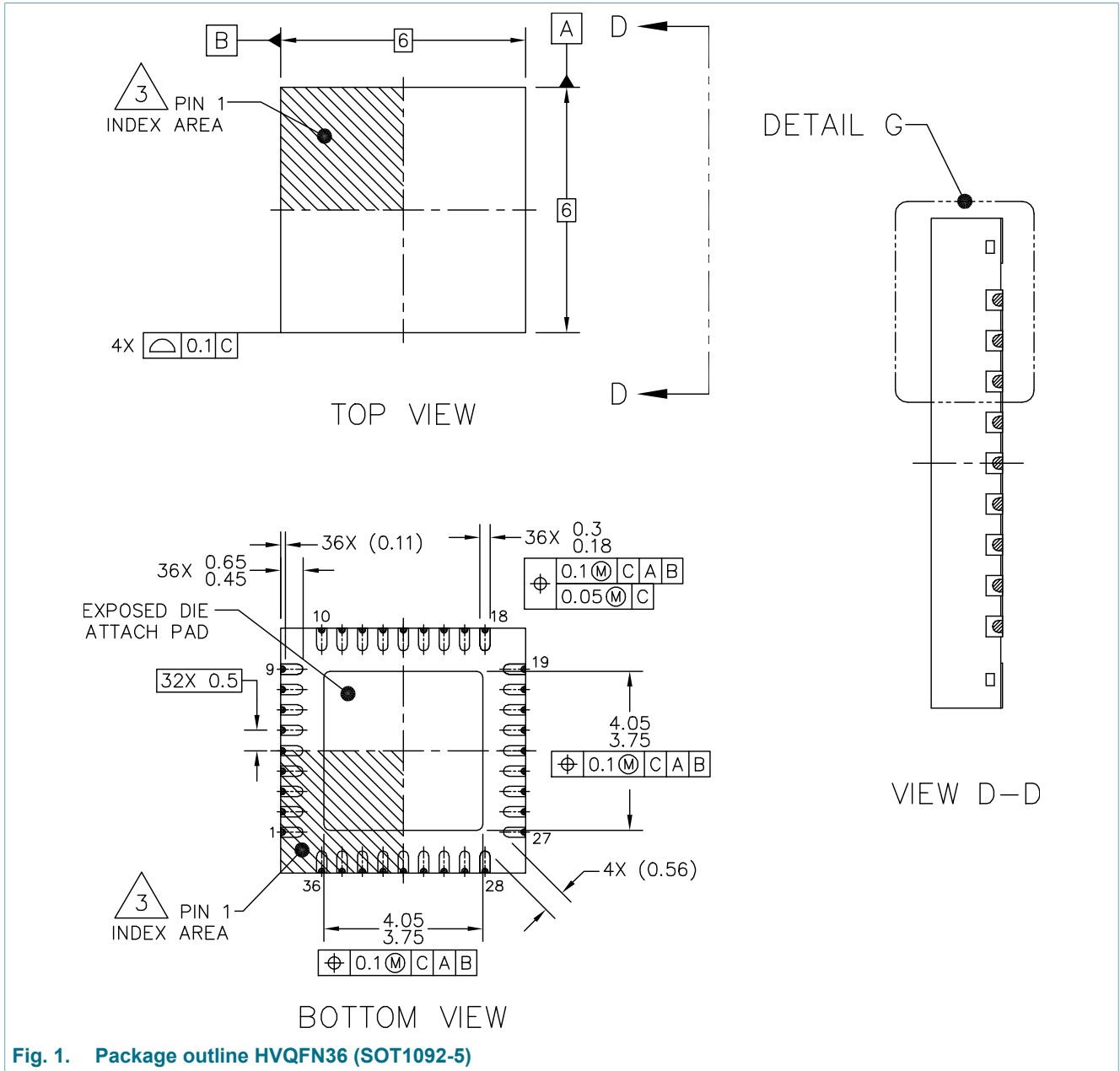
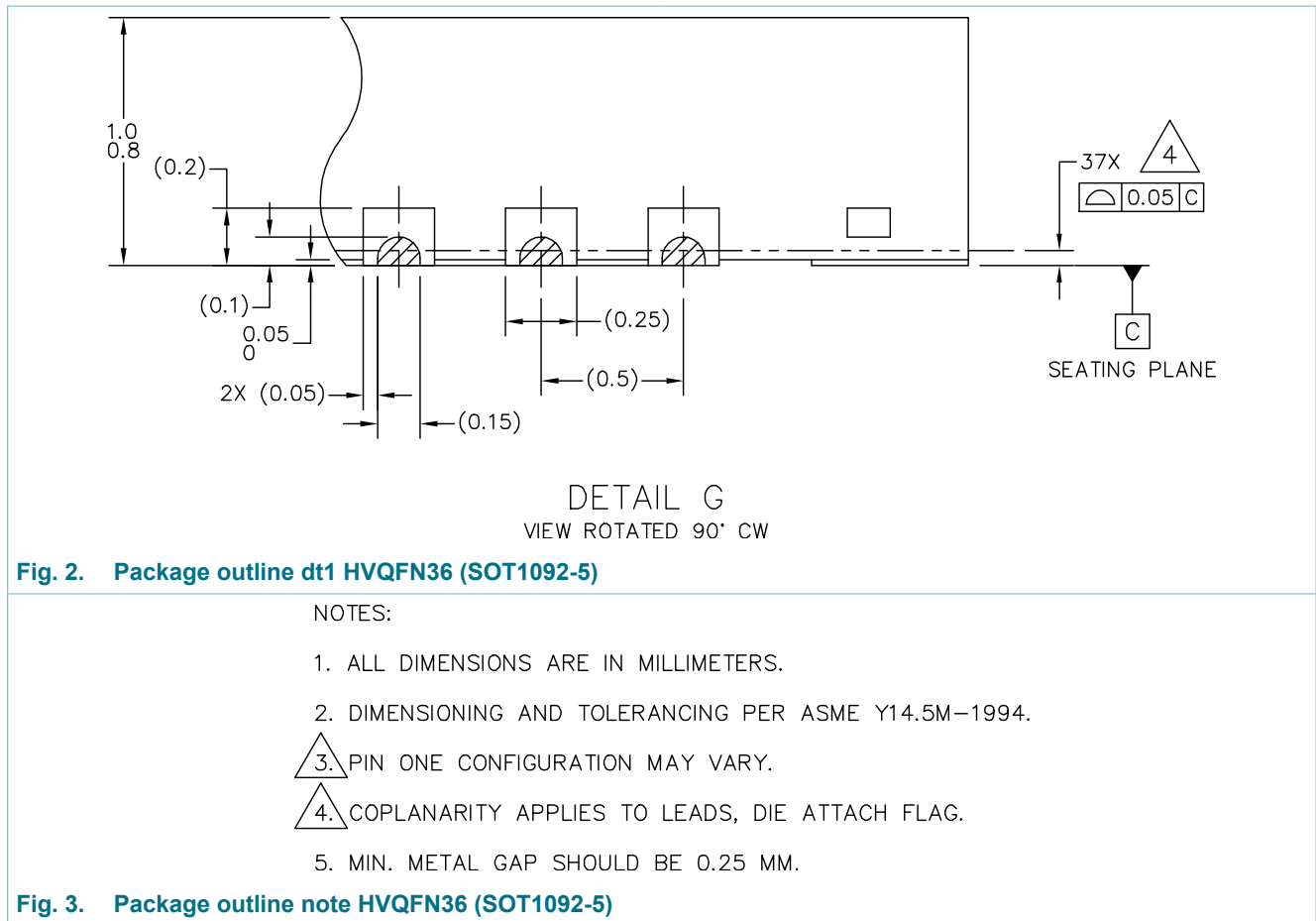


Fig. 1. Package outline HVQFN36 (SOT1092-5)

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3. Soldering

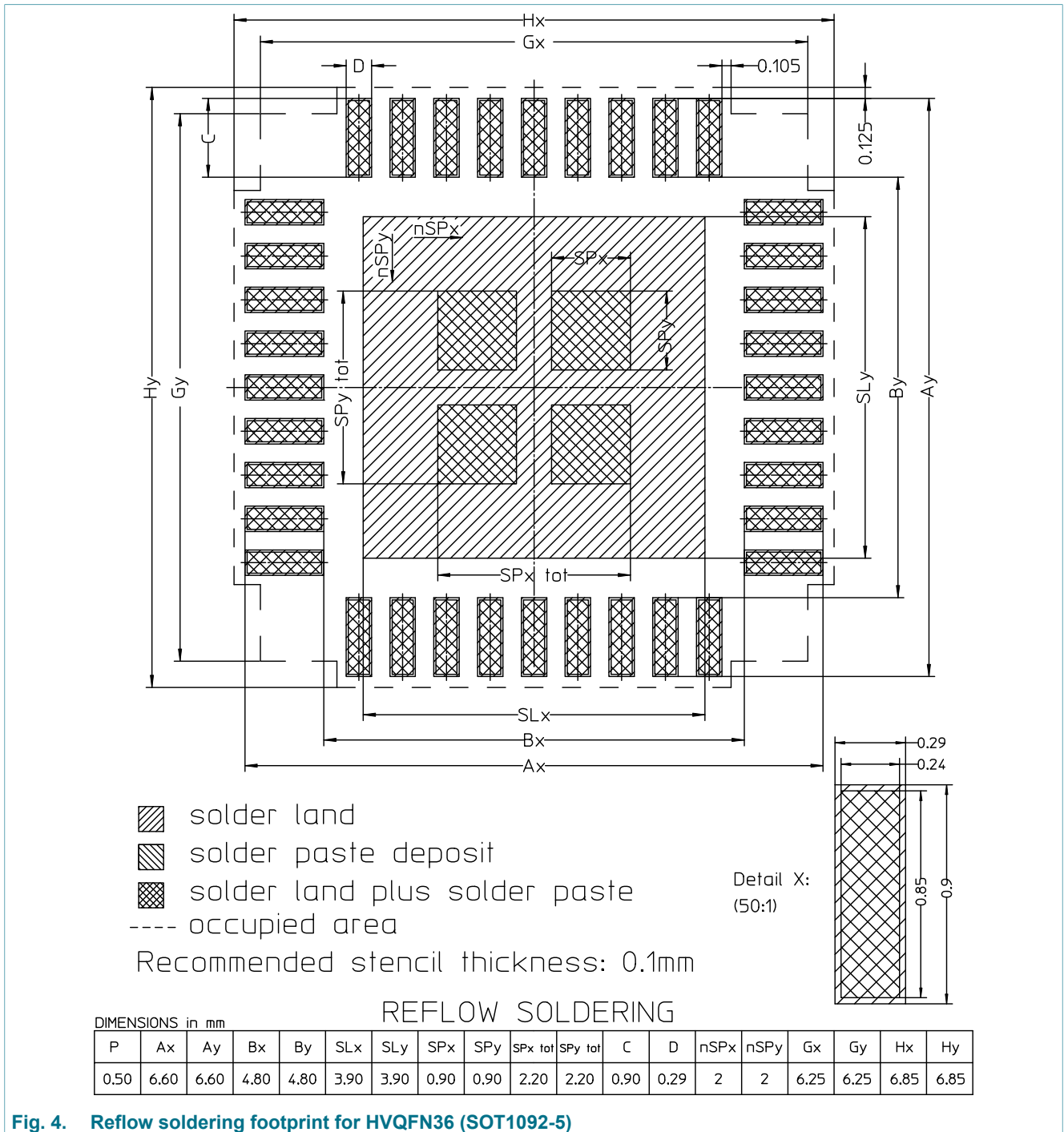


Fig. 4. Reflow soldering footprint for HVQFN36 (SOT1092-5)

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4. Legal information

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